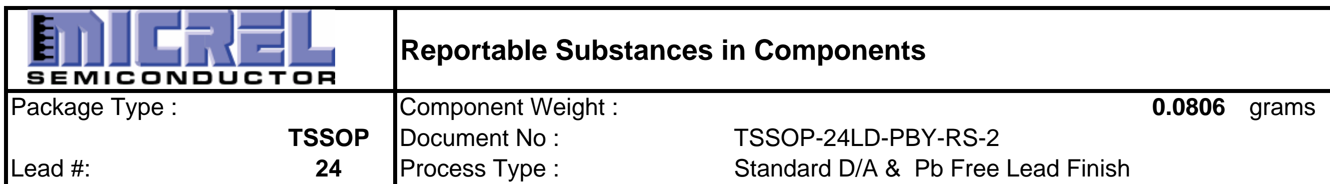

Reportable Substances in Components

Package Type :	Component Weight :		**0.0806** grams
TSSOP	Document No :	TSSOP-24LD-PBY-RS-2	
Lead #: **24**	Process Type :	Standard D/A & Pb Free Lead Finish	

No	Material	Content in %	Content in gram	Substance Name	CAS No	Content in gram	% to Content	% to Unit	PPM
1	Molding Compound	53.62%	0.04321						
				Epoxy resin	trade secret	0.00238	5.51%	2.95%	
				Phenol resin	trade secret	0.00238	5.51%	2.95%	
				SiO2 (Filler)	60676-86-0	0.03791	87.73%	47.05%	
				Sb2O3 (Antimony Trioxide)	1309-64-4	0.00017	0.39%	0.21%	
				Brominated Epoxy Resin	68541-56-0	0.00024	0.56%	0.30%	
				Carbon Black	1333-86-4	0.00013	0.30%	0.16%	
2	Copper Alloy Frame	34.57%	0.02786						
				Cu	7440-50-8	0.02628	94.33%	32.61%	
				Fe	7439-89-6	0.00006	0.22%	0.07%	745
				Pb	7439-92-1	0.00001	0.04%	0.01%	124
				Zn	7440-66-6	0.00028	1.01%	0.35%	
				Mg	7439-95-4	0.00005	0.18%	0.06%	621
				Ni	7440-02-0	0.00089	3.19%	1.10%	
				Ag	7440-22-4	0.00006	0.22%	0.07%	745
				Si	7440-21-3	0.00020	0.72%	0.25%	
				Mn	7439-96-5	0.00003	0.11%	0.04%	372
3	Spot Silver Plating	0.07%	0.00006						
				Ag	7440-22-4	0.00006	100.00%	0.07%	745
4	Silver Die Attach Epoxy	1.64%	0.00132						
				Epoxy resin	trade secret	0.00020	15.15%	0.25%	
				Aromatic Amine	trade secret	0.00007	5.30%	0.09%	869
				Ag (Filler)	7440-22-4	0.00105	79.55%	1.30%	
5	Gold Wire	1.25%	0.00101						
				Au	7440-57-5	0.00101	100.00%	1.25%	
				Be	7440-41-7	0.00000	0.00%	0.00%	
6	External Lead Plating	2.36%	0.00190						
				Sn	7440-31-5	0.00190	100.00%	2.36%	
8	Silicon Die	6.48%	0.00522						
				Si	7440-21-3	0.00522	100.00%	6.48%	

Rev	ECN	Originator	Change	Reason
A	071806HC04	E. dlSantos	New release	New